

Polycrystalline Silicon Carbide Films for Piezoresistive Elements

Yoshiharu Onuma, Kiichi Kamimura, Yoshihiro Nagura,
Cai Hao Yi and Mituhiro Kiuchi¹

Department of Electrical Engineering, Shinshu University
500 Wakasato, Nagano 380, Japan

¹Nagano Keiki Co., Ltd.
1150 Akiwa, Ueda, Nagano 386, Japan

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The experimental results regarding to the preparation and the characterization of crystalline SiC films as well as electrical properties including the piezoresistive effect have been reported in this paper. Polycrystalline SiC films were prepared on insulating substrates by plasma enhanced chemical vapor deposition (plasma-CVD) and characterized by X-ray diffraction, transmission electron diffraction and Auger analysis. It was found that polycrystalline SiC films were obtained above substrate temperatures of 600°C, and doping of a small amount of boron was effective in increasing the grain size and improving the thermal coefficients of resistance. The piezoresistive effect of the film was measured. The maximum value of the gauge factor was about 20, and was the same as that of boron-doped polycrystalline silicon thin films.

1. Introduction

Recently, many studies have been carried out on amorphous,⁽¹⁻⁷⁾ polycrystalline and single-crystalline⁽⁸⁻¹⁸⁾ SiC film growth because of its excellent properties, such as high resistance against temperature and chemicals, and many potential applications to electronic devices. However, there are few applications which are in practical use.

In general, strain gauges using semiconductors have higher sensitivity as compared with conventional metal strain gauges. Pressure sensors with SOISS (semicon-